WHAT IS CLAIMED IS:

1. A processing method for a device wafer in which a front surface of the device wafer on which a device is formed in each of chip regions partitioned by a plurality of scheduled division lines formed in a crossing relationship on the front surface of the device wafer is sealed with a sealing member and a plurality of bumps are formed individually in the chip regions of the sealing member, the processing method comprising:

an alignment step of picking up an image of a front surface side of the device wafer through the sealing member by visible light image pickup means from the front surface side of the device wafer to detect alignment marks and detecting a scheduled division line to be laser processed among the plurality of scheduled division lines based on the alignment marks; and

a division step of irradiating, after the alignment step is carried out, a laser beam of a wavelength, which is absorbed by the sealing member and the device wafer, along the scheduled division line from the front surface side of the device wafer to divide the device wafer into individual device chips sealed at the front surface thereof with the sealing member by ablation processing; wherein

the alignment step is carried out while light is irradiated in an oblique direction upon a region, whose image is to be picked up by the visible light image pickup means, by oblique light means,

the sealing member contains carbon black,

the content of the carbon black is 0.1% by mass or more and 0.2% by mass or less, and

in the alignment step, the vertical illumination of visible light image pickup means and the light from oblique illumination means are applied to the region to be imaged by visible light image pickup means.